

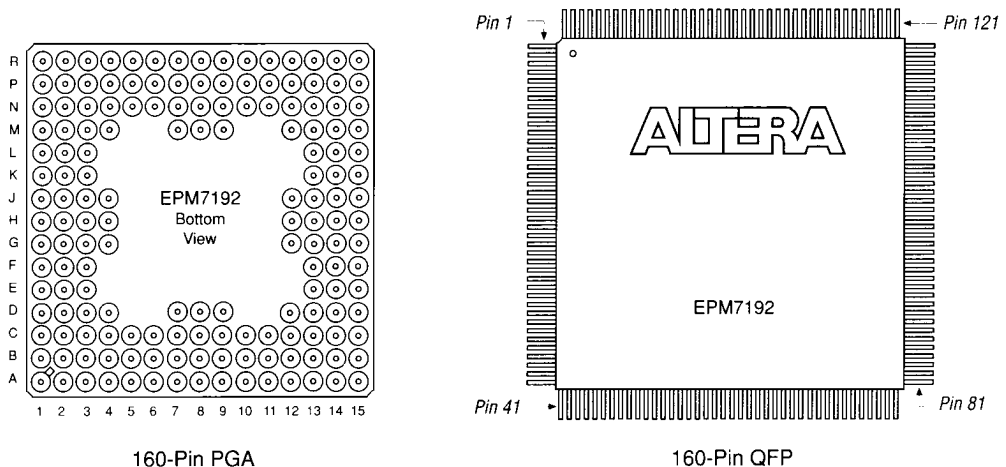
EPM7192 EPLD

Features

- ❑ High-density, erasable CMOS EPLD based on second-generation MAX architecture
 - 3,750 usable gates
 - Combinatorial speeds with $t_{PD} = 12$ ns
 - Counter frequencies up to 90.9 MHz
- ❑ Advanced 0.8-micron CMOS EEPROM technology
- ❑ Programmable I/O architecture providing up to 124 inputs or 120 outputs
- ❑ 192 advanced macrocells to efficiently implement registered and complex combinatorial logic
- ❑ Configurable expander product-term distribution allowing up to 32 product terms in a single macrocell
- ❑ Available in 160-pin packages (see Figure 30):
 - Pin-grid array (PGA)
 - Plastic quad flat pack (PQFP)

Figure 30. EPM7192 Package Pin-Out Diagrams

Package outlines not drawn to scale. See Tables 11 and 12 in this data sheet for pin-out information.



General Description

The Altera EPM7192 is a high-density, high-performance CMOS EPLD based on Altera's second-generation MAX architecture. See Figure 31. Fabricated on a 0.8-micron EEPROM technology, the EPM7192 provides 3,750 usable gates, counter speeds of 90.9 MHz and propagation delays of 12 ns. The EPM7192 architecture supports 100% TTL emulation and allows high integration of SSI, MSI, and LSI logic functions. With 192 macrocells, the EPM7192 implements complete system-level designs. It easily integrates multiple programmable logic devices such as PALs, GALs, and 22V10s.

The high density and high I/O pin count make the EPM7192 appropriate for prototyping gate arrays. The EPM7192 can accommodate both logic- and I/O-intensive designs.

Figure 31.
EPM7192 Block
Diagram

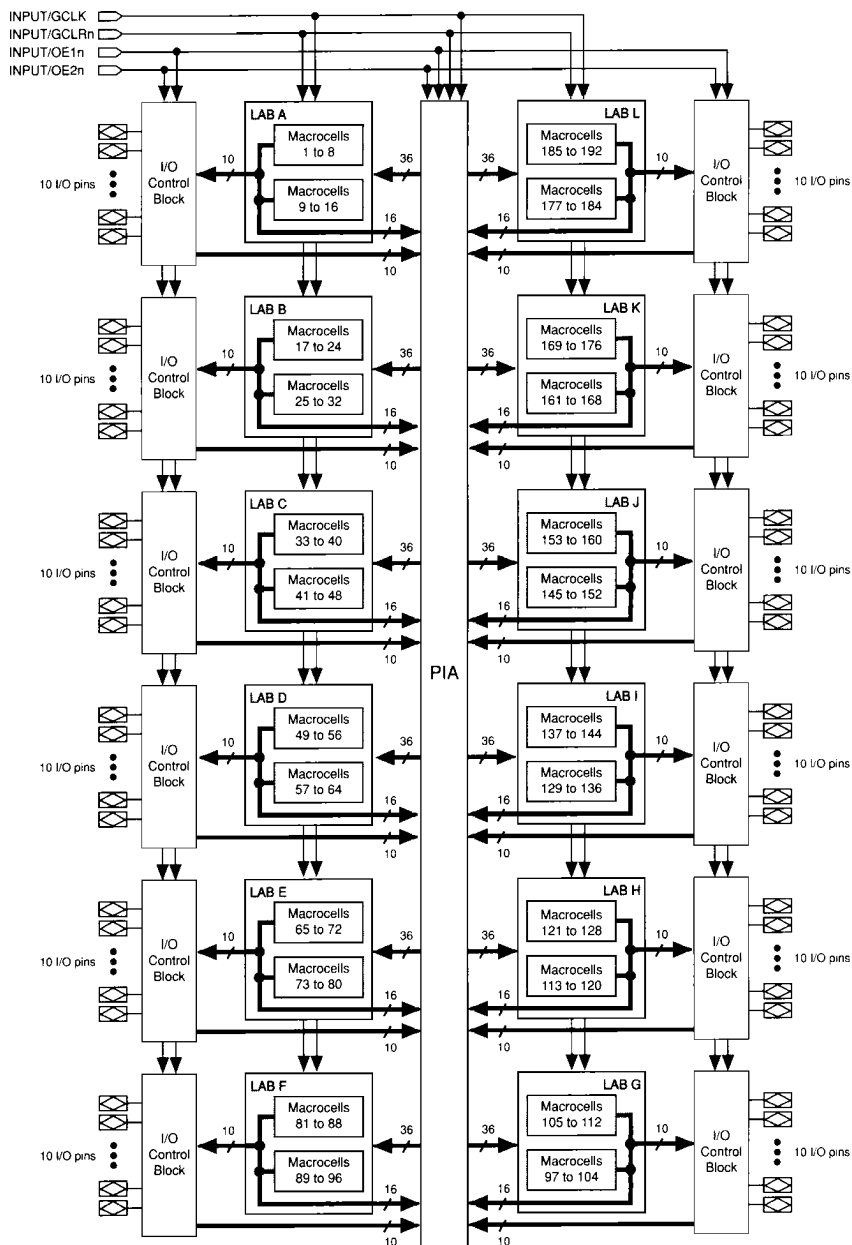


Figure 32 shows the output drive characteristics of EPM7192 I/O pins.

Figure 32. EPM7192 Output Drive Characteristics

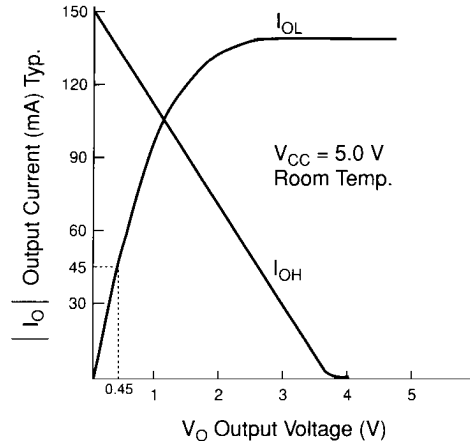


Figure 33 shows typical supply current versus frequency for the EPM7192.

Figure 33. EPM7192 I_{CC} vs. Frequency

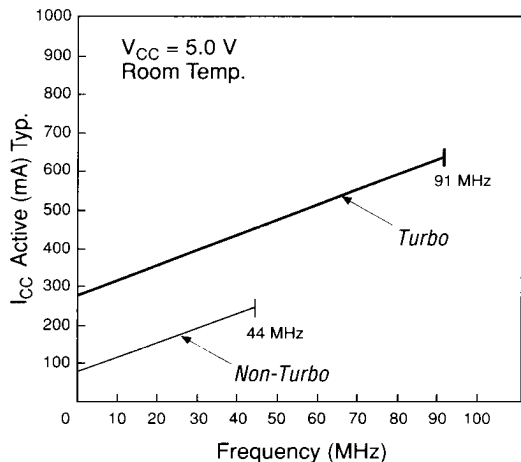
I_{CC} is calculated with the following equation:

$$I_{CC} = (1.5 \times MC_{TON}) + (0.48 \times MC_{TOFF}) + [(0.0088 \times MC) \times f_{MAX}]$$

The parameters for this equation are:

MC_{TON} = number of macrocells used with Turbo Bit on
 MC_{TOFF} = number of macrocells used with Turbo Bit off
 MC = total number of macrocells used in the design
 (MC_{TON} + MC_{TOFF})
 f_{MAX} = highest Clock frequency to the device

This measurement provides an I_{CC} estimate based on typical conditions (V_{CC} = 5.0 V, room temperature) using a typical pattern of a 16-bit loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} should be verified during operation since this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.



Absolute Maximum Ratings See *Operating Requirements for Altera Devices* in this data book.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	With respect to GND	-2.0	7.0	V
V_I	DC input voltage	Note (1)	-2.0	7.0	V
I_{MAX}	DC V_{CC} or GND current			800	mA
I_{OUT}	DC output current, per pin		-25	25	mA
P_D	Power dissipation			4000	mW
T_{STG}	Storage temperature	No bias	-65	150	°C
T_{AMB}	Ambient temperature	Under bias	-65	135	°C
T_J	Junction temperature	Under bias		150	°C

Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage		4.75	5.25	V
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
T_A	Operating temperature	For commercial use	0	70	°C
T_A	Operating temperature	For industrial use	-40	85	°C
T_C	Case temperature	For military use	-55	125	°C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

DC Operating Conditions Notes (2), (3)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	High-level input voltage		2.0		$V_{CC} + 0.3$	V
V_{IL}	Low-level input voltage		-0.3		0.8	V
V_{OH}	High-level TTL output voltage	$I_{OH} = -4$ mA DC	2.4			V
V_{OL}	Low-level output voltage	$I_{OL} = 8$ mA DC			0.45	V
I_I	Input leakage current	$V_I = V_{CC}$ or GND	-10		10	μA
I_{OZ}	Tri-state output off-state current	$V_O = V_{CC}$ or GND	-40		40	μA
I_{CC1}	V_{CC} supply current (low-power mode, standby)	$V_I =$ GND, No load Note (4)		130		mA
I_{CC2}	V_{CC} supply current (low-power mode, active)	$V_I =$ GND, No load, $f = 1.0$ MHz, Note (4)		135		mA

Capacitance Note (5)

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		15	pF
C_{OUT}	Output capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		15	pF

AC Operating Conditions Note (3)

External Timing Parameters			EPM7192-12		EPM7192-15		EPM7192-20		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
t_{PD1}	Input to non-registered output	C1 = 35 pF		12		15		20	ns
t_{PD2}	I/O input to non-registered output			12		15		20	ns
t_{SU}	Global clock setup time		10		11		12		ns
t_H	Global clock hold time		0		0		0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		6		9		12	ns
t_{CH}	Global clock high time		4		5		6		ns
t_{CL}	Global clock low time		4		5		6		ns
t_{ASU}	Array clock setup time		4		5		5		ns
t_{AH}	Array clock hold time		4		5		5		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		12		15		20	ns
t_{ACH}	Array clock high time		5		6		8		ns
t_{ACL}	Array clock low time		5		6		8		ns
t_{CNT}	Minimum global clock period			11		13		16	ns
f_{CNT}	Max. internal global clock frequency	Note (4)	90.9		76.9		62.5		MHz
t_{ACNT}	Minimum array clock period			11		13		16	ns
f_{ACNT}	Max. internal array clock frequency	Note (4)	90.9		76.9		62.5		MHz
f_{MAX}	Maximum clock frequency	Note (6)	125		100		83.3		MHz
Internal Timing Parameters			EPM7192-12		EPM7192-15		EPM7192-20		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
t_{IN}	Input pad and buffer delay			2		3		3	ns
t_{IO}	I/O input pad and buffer delay			2		3		3	ns
t_{SEXP}	Shared expander delay			7		8		9	ns
t_{PEXP}	Parallel expander delay			1		2		2	ns
t_{LAD}	Logic array delay			5		5		8	ns
t_{LAC}	Logic control array delay			5		5		8	ns
t_{OD}	Output buffer and pad delay	C1 = 35 pF		3		4		5	ns
t_{ZX}	Output buffer enable delay			6		6		9	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6		6		9	ns
t_{SU}	Register setup time		4		5		4		ns
t_H	Register hold time		4		5		5		ns
t_{RD}	Register delay			1		1		1	ns
t_{COMB}	Combinatorial delay			1		1		1	ns
t_{IC}	Array clock delay			5		5		8	ns
t_{EN}	Register enable time			5		5		8	ns
t_{GLOB}	Global control delay			0		1		3	ns
t_{PRE}	Register preset time			3		4		4	ns
t_{CLR}	Register clear time			3		4		4	ns
t_{PIA}	Prog. Interconnect Array delay			1		2		3	ns
t_{LPA}	Low power adder	Note (7)		12		13		15	ns

Notes to tables:

- (1) Minimum DC input is -0.3 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 7.0 V for periods shorter than 20 ns under no-load conditions.
- (2) Typical values are for $T_A = 25^\circ\text{C}$ and $V_{CC} = 5.0$ V.
- (3) Operating conditions: $V_{CC} = 5.0\text{ V} \pm 5\%$, $T_A = 0^\circ\text{C}$ to 70°C for commercial use.
 $V_{CC} = 5.0\text{ V} \pm 10\%$, $T_A = -40^\circ\text{C}$ to 85°C for industrial use.
 $V_{CC} = 5.0\text{ V} \pm 10\%$, $T_C = -55^\circ\text{C}$ to 125°C for military use.
- (4) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB. I_{CC} measured at 0°C .
- (5) Capacitance measured at 25°C . Sample-tested only. The OE1n pin (high-voltage pin during programming) has a maximum capacitance of 20 pF.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

Product Availability

Product Grade		Availability
Commercial Temp.	$(0^\circ\text{C}$ to $70^\circ\text{C})$	EPM7192-12, EPM7192-15, EPM7192-20
Industrial Temp.	$(-40^\circ\text{C}$ to $85^\circ\text{C})$	EPM7192-20
Military Temp.	$(-55^\circ\text{C}$ to $125^\circ\text{C})$	Consult factory
MIL-STD-883-Compliant	Note (1)	See <i>Military Products</i> in this data book.

Note:

- (1) MIL-STD-883-compliant product specifications are provided in this data book and in Military Product Drawings (MPDs). However, only MPDs should be used to prepare Source Control Drawings (SCDs). MPDs are available from Altera Marketing at (408) 894-7000.

New Speed-Grade Ordering Codes

Speed-grade codes for EPM7192 devices have changed. The following table provides the new codes, which indicate the actual propagation delay times.

Old Speed Grade	New Speed Grade
EPM7192-1	EPM7192-12
EPM7192-2	EPM7192-15
EPM7192-3	EPM7192-20

Pin-Out Information

Tables 11 and 12 provide pin-out information for the EPM7192 packages.

Table 11. EPM7192 Dedicated Pin-Outs

Dedicated Pin	160-Pin PGA	160-Pin QFP
GCLK	M8	139
GCLRn	N8	141
OE1n	P8	140
OE2n	R8	142
GND	C4, C6, C11, D7, D9, D13, G4, H12, J4, M7, M9, M13, N4, N11	3, 18, 32, 47, 57, 64, 66, 81, 96, 111, 126, 138, 143, 148
VCC	C5, C7, C9, C10, C12, D3, G12, H4, J12, M3, N5, N7, N9, N12	10, 25, 40, 55, 56, 65, 74, 89, 103, 118, 133, 137, 144, 155
No Connect (N.C.)	A1, A2, A14, A15, R1, R2, R14, R15	1, 11, 39, 54, 67, 82, 110, 120

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Table 12. EPM7192 I/O Pin-Outs (Part 1 of 2)

MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP
1	A	M12	156	17	B	L14	8	33	C	H14	21
2	A	—	—	18	B	—	—	34	C	—	—
3	A	P11	154	19	B	M14	7	35	C	J13	20
4	A	—	—	20	B	—	—	36	C	—	—
5	A	P12	153	21	B	M15	6	37	C	H15	19
6	A	P10	152	22	B	N14	5	38	C	J15	17
7	A	—	—	23	B	—	—	39	C	—	—
8	A	R12	151	24	B	N15	4	40	C	J14	16
9	A	N10	150	25	B	P15	2	41	C	K15	15
10	A	—	—	26	B	—	—	42	C	—	—
11	A	R11	149	27	B	N13	160	43	C	K13	14
12	A	—	—	28	B	—	—	44	C	—	—
13	A	R10	147	29	B	P14	159	45	C	L15	13
14	A	P9	146	30	B	P13	158	46	C	K14	12
15	A	—	—	31	B	—	—	47	C	—	—
16	A	R9	145	32	B	R13	157	48	C	L13	9
49	D	D15	33	65	E	B12	45	81	F	D8	60
50	D	—	—	66	E	—	—	82	F	—	—
51	D	E15	31	67	E	B13	44	83	F	A9	59
52	D	—	—	68	E	—	—	84	F	—	—
53	D	E14	30	69	E	C13	43	85	F	C8	58
54	D	F15	29	70	E	B14	42	86	F	B9	53
55	D	—	—	71	E	—	—	87	F	—	—
56	D	F13	28	72	E	C14	41	88	F	A10	52
57	D	G14	27	73	E	D12	38	89	F	B10	51
58	D	—	—	74	E	—	—	90	F	—	—
59	D	F14	26	75	E	B15	37	91	F	A11	50
60	D	—	—	76	E	—	—	92	F	—	—
61	D	G13	24	77	E	D14	36	93	F	B11	49
62	D	G15	23	78	E	C15	35	94	F	A12	48
63	D	—	—	79	E	—	—	95	F	—	—
64	D	H13	22	80	E	E13	34	96	F	A13	46

Table 12. EPM7192 I/O Pin-Outs (Part 2 of 2)

MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP
97	G	A8	61	113	H	A3	76	129	I	E3	88
98	G	—	—	114	H	—	—	130	I	—	—
99	G	B8	62	115	H	B4	77	131	I	F3	90
100	G	—	—	116	H	—	—	132	I	—	—
101	G	A7	63	117	H	B3	78	133	I	E2	91
102	G	A6	68	118	H	C3	79	134	I	F2	92
103	G	—	—	119	H	—	—	135	I	—	—
104	G	B7	69	120	H	B2	80	136	I	E1	93
105	G	A5	70	121	H	B1	83	137	I	G3	94
106	G	—	—	122	H	—	—	138	I	—	—
107	G	B6	71	123	H	C2	84	139	I	F1	95
108	G	—	—	124	H	—	—	140	I	—	—
109	G	A4	72	125	H	C1	85	141	I	G1	97
110	G	B5	73	126	H	D2	86	142	I	G2	98
111	G	—	—	127	H	—	—	143	I	—	—
112	G	D4	75	128	H	D1	87	144	I	H1	99
145	J	H2	100	161	K	L2	113	177	L	R3	125
146	J	—	—	162	K	—	—	178	L	—	—
147	J	J1	101	163	K	N1	114	179	L	R4	127
148	J	—	—	164	K	—	—	180	L	—	—
149	J	H3	102	165	K	L3	115	181	L	M4	128
150	J	J3	104	166	K	P1	116	182	L	R5	129
151	J	—	—	167	K	—	—	183	L	—	—
152	J	K1	105	168	K	M2	117	184	L	P5	130
153	J	J2	106	169	K	N2	119	185	L	R6	131
154	J	—	—	170	K	—	—	186	L	—	—
155	J	K2	107	171	K	P2	121	187	L	P6	132
156	J	—	—	172	K	—	—	188	L	—	—
157	J	K3	108	173	K	N3	122	189	L	N6	134
158	J	L1	109	174	K	P3	123	190	L	R7	135
159	J	—	—	175	K	—	—	191	L	—	—
160	J	M1	112	176	K	P4	124	192	L	P7	136

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